

RKP3000DKL

Silicon Epitaxial Planar Pin Diode for Wireless LAN

REJ03G0418-0100 Rev.1.00 Oct 18, 2004

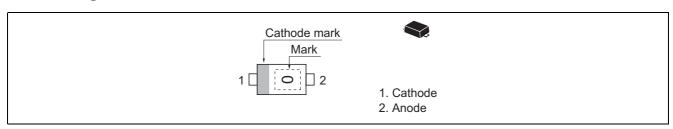
Features

- Suitable for an antenna switches of wireless LAN and a cordless telephone.
- Super -Low capacitance.(C = 0.25 pF max)
- Low forward resistance. (rf = $3.7 \Omega \text{ max}$)
- Extremely small Flat Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
RKP3000DKL	0	EFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	30	V
Forward current	I _F	50	mA
Power dissipation	Pd	100	mW
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

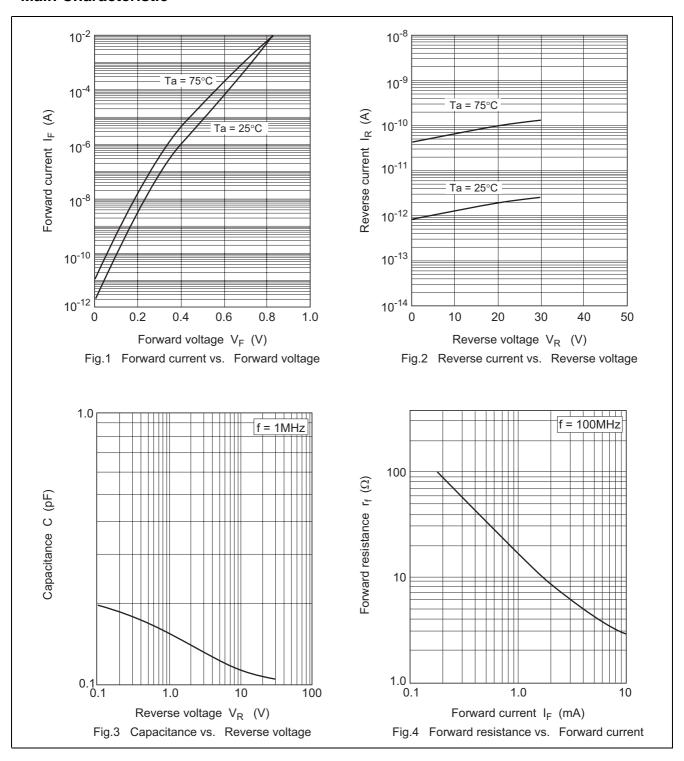
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	_	_	100	nA	V _R = 30 V
Forward voltage	V _F	_	_	1.0	V	I _F = 10 mA
Capacitance	С	_	_	0.25	pF	$V_R = 1 V, f = 1 MHz$
Forward resistance	r _f	_	_	3.7	Ω	I _F = 10 mA, f = 100 MHz

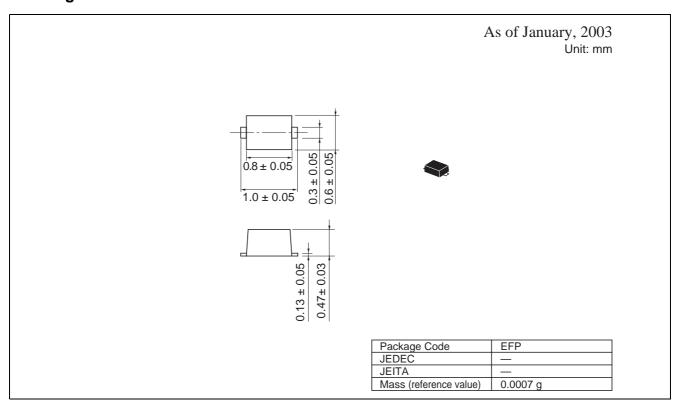
Notes: 1. Please do not use the soldering iron due to avoid high stress to the EFP package.

2. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions



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Renesas Technology Europe Limited Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.

Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.
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Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001